



SOT786-2

plastic thermal enhanced small outline package; 8 leads;
body width 3.9 mm; exposed die pad

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HSO8
Package type industry code	HSO8
Package style descriptive code	HSO (thermal enhanced small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	2-8-2013

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.8	-	4.9	5	mm
E	package width	3.8	-	3.9	4	mm
A	seated height	[tbd]	-	1.7	1.7	mm
A ₂	package height	1.4	-	1.5	1.6	mm
n ₂	actual quantity of termination	-	-	8	-	

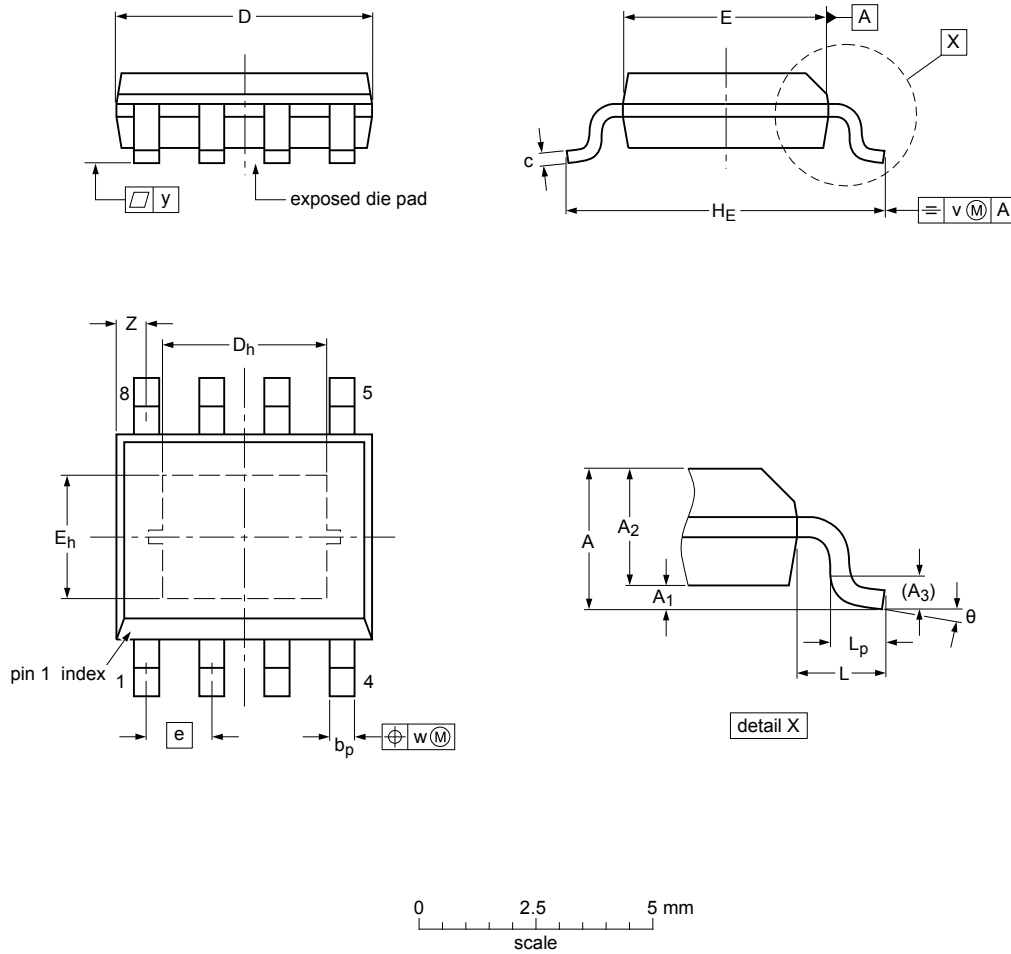


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2. Package outline

HSO8: plastic thermal enhanced small outline package;
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Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	D _h	E ⁽²⁾	E _h	e	H _E	L	L _p	v	w	y	Z ⁽¹⁾	θ
max		0.1	1.6		0.49	0.25	5.0	3.17	4.0	2.49		6.2		1.0				0.8	8°
nom	1.7			0.25							1.27		1.05		0.25	0.25	0.1		
min		0.0	1.4		0.36	0.19	4.8	2.97	3.8	2.29		5.8		0.4				0.3	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

sot786-2_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT786-2					-13-08-02- 14-05-27

Fig. 1. Package outline HSO8 (SOT786-2)

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3. Legal information

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Date of release: 8 February 2016
